



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of
Ehmke *et al.*
Appln. No.: 10/747,862
Filed: 12/29/2003
For: Method for Fabricating a Lid for a
Wafer Level Packaged Optical MEMS Device

Docket: TI-34210
Art Unit: 2815
Examiner: Clark, Sheila V.
Conf. No.: 2777

LETTER TO OFFICIAL DRAFTSPERSON

December 22, 2004

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)	
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date below.	
<i>Sue Short</i>	<i>1/4/2005</i>
Sue Short	Date

Draftsperson:

Applicants submit five (5) sheets of formal drawings. Applicants believe that these drawings incorporate all required drawing changes imposed during the prosecution of this application. Applicants believe this application is now in condition for allowance.

Charge any necessary fee to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,

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